Amendments to the Specification:

Please replace paragraph **[0003]** with the following amended paragraph:

[0001] FIG. 1 shows a cross section of a conventional optocoupler DIP package **10**. The illustrated optocoupler **10** includes a lead frame **24** comprising leads **24(a)**, **24(b)** (*i.e.*, pins). An optical emitter device **12** is mounted on one lead **24(a)**. An optical receiver device **14** is mounted on the other lead **24(b)**. The optical receiver device **14** generates an electrical signal after receiving light **20** generated by the optical emitter device **12**. The optical emitter device **12** is electrically coupled to the lead **24(a)** through its bottom surface, and to another lead (not shown) via a wire **11**. Similarly, optical receiver device **14** is electrically coupled to the lead **24(b)** through the bottom surface and to another lead (not shown) via a wire **13**. It will be recognized by those skilled in the art that the optical emitter device **12** operates with two electrical connections, an anode and a cathode. These connections are thus provided by the wire **11** and the lead **24(a)**. Similarly, optical receiver device **14** operates with two electrical connections, typically an emitter and a collector. These connections are provided by the wire **13** and lead **24(b)**. The optocoupler package **10** further includes an optically transmissive medium **16**. A molding compound **18** encases the leadframe **24**, optical emitter device **12**, optical receiver device **14**, and the optically transmissive medium **16**.